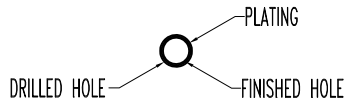


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DATE	REV	REVISION RECORD	APP	DR	CK
5-10 06	B	ECO 25921	TK	ME	TK
8-14 06	C	ECO 26510	TK	YK	TK
8-5 08	D	ECO 29799	RCW	YK	RCW
10-14 08	E	ECO 30108		YK	

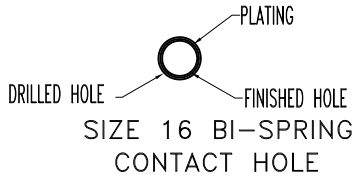


SIZE 20 AND 22 OMEGA CONTACT HOLE

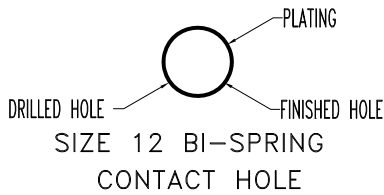
SIZE 20-22 OMEGA CONTACT HOLE			
BOARD TYPE	RECOMMENDED DRILLED HOLE SIZE	RECOMMENDED PLATING	FINISHED HOLE SIZES
TIN-LEAD SOLDER PCB	$\varnothing 1.150 \pm 0.025$ [$\varnothing 0.0453 \pm 0.0010$]	15 μ [0.0006] MINIMUM SOLDER OVER 25 μ [0.0010] MIN. COPPER	$\varnothing 1.000 + 0.090 - 0.060$ [$\varnothing 0.0394 + 0.0035 - 0.0024$]
COPPER PCB	$\varnothing 1.19 \pm 0.025$ [$\varnothing 0.047 \pm 0.001$]	25 μ [0.0010] MIN. COPPER	$\varnothing 1.09 \pm 0.05$ [$\varnothing 0.043 \pm 0.002$]
IMMERSION TIN PCB	$\varnothing 1.19 \pm 0.025$ [$\varnothing 0.047 \pm 0.001$]	0.85 $\pm 0.15\mu$ [0.000033 ± 0.000006] IMMERSION TIN OVER 25 μ [0.0010] MIN. COPPER	$\varnothing 1.09 \pm 0.05$ [$\varnothing 0.043 \pm 0.002$]
IMMERSION SILVER PCB	$\varnothing 1.19 \pm 0.025$ [$\varnothing 0.047 \pm 0.001$]	0.34 $\pm 0.17\mu$ [0.000013 ± 0.000007] IMMERSION SILVER OVER 25 μ [0.0010] MIN. COPPER	$\varnothing 1.09 \pm 0.05$ [$\varnothing 0.043 \pm 0.002$]
ELECTROLESS NICKEL/IMMERSION GOLD PCB	$\varnothing 1.19 \pm 0.025$ [$\varnothing 0.047 \pm 0.001$]	0.05 μ [0.000002] MIN. IMMERSION GOLD OVER 4.5 $\pm 1.5\mu$ [0.000177 ± 0.000059] ELECTROLESS NICKEL PER IPC-4552 OVER 25 μ [0.0010] MIN. COPPER	$\varnothing 1.09 \pm 0.05$ [$\varnothing 0.043 \pm 0.002$]

 POSITRONIC INDUSTRIES INC. www.connectpositronic.com		COMPLIANT TERMINATION CONTACTS		SCALE N.T.S.	DRAWN BY TKEPLEY
DECIMAL TOL. ± 0.38 [0.015]		TITLE PLATED PCB HOLES			
ANGULAR TOL. $\pm 5^\circ$		DATE 8-5-05	DRAWING NUMBER SK6370	SHEET 1 OF 3	
					REV. E

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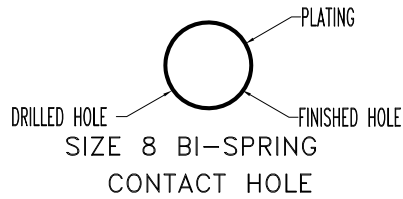


SIZE 16 PRESS-FIT CONTACT HOLE			
BOARD TYPE	RECOMMENDED DRILLED HOLE SIZE	RECOMMENDED PLATING	FINISHED HOLE SIZES
TIN-LEAD SOLDER PCB	$\varnothing 1.750 \pm 0.025$ [$\varnothing 0.069 \pm 0.001$]	15 μ [0.0006] MINIMUM SOLDER OVER 25 μ [0.0010] MIN. COPPER	$\varnothing 1.600 + 0.090 - 0.060$ [$\varnothing 0.0630 + 0.0035 - 0.0024$]
COPPER PCB	$\varnothing 1.750 \pm 0.025$ [$\varnothing 0.069 \pm 0.001$]	25 μ [0.0010] MIN. COPPER	$\varnothing 1.600 + 0.090 - 0.060$ [$\varnothing 0.0630 + 0.0035 - 0.0024$]
IMMERSION TIN PCB	$\varnothing 1.750 \pm 0.025$ [$\varnothing 0.069 \pm 0.001$]	0.85 $\pm 0.15\mu$ [0.000033 ± 0.000006] IMMERSION TIN OVER 25 μ [0.0010] MIN. COPPER	$\varnothing 1.600 + 0.090 - 0.060$ [$\varnothing 0.0630 + 0.0035 - 0.0024$]
IMMERSION SILVER PCB	$\varnothing 1.750 \pm 0.025$ [$\varnothing 0.069 \pm 0.001$]	0.34 $\pm 0.17\mu$ [0.000013 ± 0.000007] IMMERSION SILVER OVER 25 μ [0.0010] MIN. COPPER	$\varnothing 1.600 + 0.090 - 0.060$ [$\varnothing 0.0630 + 0.0035 - 0.0024$]
ELECTROLESS NICKEL/IMMERSION GOLD PCB	$\varnothing 1.750 \pm 0.025$ [$\varnothing 0.069 \pm 0.001$]	0.05 μ [0.000002] MIN. IMMERSION GOLD OVER 4.5 $\pm 1.5\mu$ [0.000177 ± 0.000059] ELECTROLESS NICKEL PER IPC-4552 OVER 25 μ [0.0010] MIN. COPPER	$\varnothing 1.600 + 0.090 - 0.060$ [$\varnothing 0.0630 + 0.0035 - 0.0024$]



SIZE 12 BI-SPRING CONTACT HOLE			
BOARD TYPE	RECOMMENDED DRILLED HOLE SIZE	RECOMMENDED PLATING	FINISHED HOLE SIZES
TIN-LEAD SOLDER PCB	$\varnothing 2.59 \pm 0.025$ [$\varnothing 0.102 \pm 0.001$]	15 μ [0.0006] MINIMUM SOLDER OVER 25 μ [0.0010] MIN. COPPER	$\varnothing 2.44 \pm 0.05$ [$\varnothing 0.096 \pm 0.002$]
COPPER PCB	$\varnothing 2.59 \pm 0.025$ [$\varnothing 0.102 \pm 0.001$]	25 μ [0.0010] MIN. COPPER	$\varnothing 2.44 \pm 0.05$ [$\varnothing 0.096 \pm 0.002$]
IMMERSION TIN PCB	$\varnothing 2.59 \pm 0.025$ [$\varnothing 0.102 \pm 0.001$]	0.85 $\pm 0.15\mu$ [0.000033 ± 0.000006] IMMERSION TIN OVER 25 μ [0.0010] MIN. COPPER	$\varnothing 2.44 \pm 0.05$ [$\varnothing 0.096 \pm 0.002$]
IMMERSION SILVER PCB	$\varnothing 2.59 \pm 0.025$ [$\varnothing 0.102 \pm 0.001$]	0.34 $\pm 0.17\mu$ [0.000013 ± 0.000007] IMMERSION SILVER OVER 25 μ [0.0010] MIN. COPPER	$\varnothing 2.44 \pm 0.05$ [$\varnothing 0.096 \pm 0.002$]
ELECTROLESS NICKEL/IMMERSION GOLD PCB	$\varnothing 2.59 \pm 0.025$ [$\varnothing 0.102 \pm 0.001$]	0.05 μ [0.000002] MIN. IMMERSION GOLD OVER 4.5 $\pm 1.5\mu$ [0.000177 ± 0.000059] ELECTROLESS NICKEL PER IPC-4552 OVER 25 μ [0.0010] MIN. COPPER	$\varnothing 2.44 \pm 0.05$ [$\varnothing 0.096 \pm 0.002$]

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SIZE 8 BI-SPRING CONTACT HOLE			
BOARD TYPE	RECOMMENDED DRILLED HOLE SIZE	RECOMMENDED PLATING	FINISHED HOLE SIZES
TIN-LEAD SOLDER PCB	$\varnothing 3.180 \pm 0.025$ [$\varnothing 0.125 \pm 0.001$]	15 μ [0.0006] MINIMUM SOLDER OVER 25 μ [0.0010] MIN. COPPER	$\varnothing 3.02 \pm 0.05$ [$\varnothing 0.119 \pm 0.002$]
COPPER PCB	$\varnothing 3.180 \pm 0.025$ [$\varnothing 0.125 \pm 0.001$]	25 μ [0.0010] MIN. COPPER	$\varnothing 3.02 \pm 0.05$ [$\varnothing 0.119 \pm 0.002$]
IMMERSION TIN PCB	$\varnothing 3.180 \pm 0.025$ [$\varnothing 0.125 \pm 0.001$]	0.85 $\pm 0.15\mu$ [0.000033 ± 0.000006] IMMERSION TIN OVER 25 μ [0.0010] MIN. COPPER	$\varnothing 3.02 \pm 0.05$ [$\varnothing 0.119 \pm 0.002$]
IMMERSION SILVER PCB	$\varnothing 3.180 \pm 0.025$ [$\varnothing 0.125 \pm 0.001$]	0.34 $\pm 0.17\mu$ [0.000013 ± 0.000007] IMMERSION SILVER OVER 25 μ [0.0010] MIN. COPPER	$\varnothing 3.02 \pm 0.05$ [$\varnothing 0.119 \pm 0.002$]
ELECTROLESS NICKEL/IMMERSION GOLD PCB	$\varnothing 3.180 \pm 0.025$ [$\varnothing 0.125 \pm 0.001$]	0.05 μ [0.000002] MIN. IMMERSION GOLD OVER 4.5 $\pm 1.5\mu$ [0.000177 ± 0.000059] ELECTROLESS NICKEL PER IPC-4552 OVER 25 μ [0.0010] MIN. COPPER	$\varnothing 3.02 \pm 0.05$ [$\varnothing 0.119 \pm 0.002$]